

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/17/2022

Details for "CD4015BMT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
CD4015BMT	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D 16	3.91x9.9x1.58	159.2

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.080637	99.99876	999988	0.05066	507
Precious Metals	Silver	7440-22-4	0.000001	0.00124	12	0.000001	0
Sub-Total			0.080638	100	1000000	0.050661	507
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.54995	79.000027	790000	0.345507	3455
Thermoplastics	Epoxy	85954-11-6	0.146189	20.999973	210000	0.091843	918
Sub-Total			0.696139	100	1000000	0.43735	4374
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	44.099426	97.424997	974250	27.705537	277055
Copper and Its Alloys	Iron	7439-89-6	1.08636	2.4	24000	0.682507	6825
Copper and Its Alloys	Phosphorus	7723-14-0	0.00679	0.015001	150	0.004266	43
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.01358	0.030001	300	0.008532	85
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.01358	0.030001	300	0.008532	85
Zinc and Its Alloys	Zinc	7440-66-6	0.045265	0.1	1000	0.028438	284
Sub-Total			45.265001	100	1000000	28.437811	284378
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.9512	95.12	951200	0.597593	5976
Precious Metals	Gold	7440-57-5	0.0078	0.78	7800	0.0049	49
Precious Metals	Palladium	7440-05-3	0.041	4.1	41000	0.025758	258
Sub-Total			1	100	1000000	0.628252	6283
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	96.44676	88	880000	60.592836	605928
Other Plastics and Rubber	Carbon Black	1333-86-4	0.328796	0.3	3000	0.206567	2066
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.602792	0.55	5500	0.378705	3787
Thermoplastics	Epoxy	85954-11-6	12.220243	11.15	111500	7.677388	7674
Sub-Total			109.598591	100	1000000	68.855495	688555
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.531518	100	1000000	1.59043	15904
Sub-Total			2.531518	100	1000000	1.59043	15904
Total			159.171887			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are for the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. [See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." [For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq008>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.